

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0003] as follows:

For example, JP-A No. 6-251993~~a first patent document~~ describes an electronic component assembly constituted by plural chip components each having a plate shape and having cutouts formed at its four corners and electrodes at its opposite end surfaces, wherein the plural chip components are connected and bonded to one another at their side surfaces on which no electrodes are formed. Further, JP-A No. 2001-223455~~a second patent document~~ describes a technique for fabricating an electric component assembly constituted by two or more chip components having a rectangular-parallelpiped shape and including electrodes at their opposite ends which are stacked in a direction perpendicular to the longitudinal directions of the chip components with an insulation layer interposed therebetween and then mounting the electronic component assembly onto a board including electrode patterns formed thereon. Further, JP-A No. 63-60593~~a third patent document~~ discloses two same-sized chip condensers stacked perpendicularly to the main surface of a board.

Please amend paragraph [0004] as follows:

Further, Fig. 7 in Pamphlet of International Publication No. 01/048821~~a fourth patent document~~ and Fig. 20 in a JP-A No. 2003-108963~~fifth patent document~~ describe a substrate structure constituted by a first substrate, a second substrate which is electrically connected onto the first substrate through chip components such as resistors and condensers, and other electronic components mounted on the upper and lower main surfaces of the second substrate. In the structure described in Pamphlet of International Publication No. 01/048821~~the fourth~~ and JP-A No. 2003-108963~~fifth patent documents~~, chip components between the first substrate and the second substrate are provided instead of conductors for connecting both the substrates to each other, while the other electric components which do not contribute to the electrical connection between the first and second substrates occupy a greater part of the region between these substrates.

Please delete paragraph [0005].

Please cancel the heading “Disclosure of the Invention,” in line 20 on page 3 of the specification.

Please cancel the heading “Subject to be solved by the Invention,” in line 21 on page 3 of the specification.

Please amend paragraph [0007] as follows:

Further, the technique disclosed in JP-A No. 63-60593~~the third patent document~~ is merely stacking the same type of chip condensers vertically and can be replaced by the use of a single chip condenser with an equivalent capacitance without stacking chip condensers. Further, a limited region of a circuit board can be used for stacking chip condensers due to the restriction on their capacitances and the like, and therefore, such stacking of chip condensers does not significantly contribute to the reduction of the size of the circuit board.

Please amend paragraph [0008] as follows:

Further, the substrate structure disclosed in Pamphlet of International Publication No. 01/048821~~the fourth~~ and JP-A No. 2003-108963~~fifth patent documents~~ can realize high-density mounting with multiple layers, but such high-density mounting requires significant changes in the design of the circuit board. Thereby, such a substrate structure cannot address the requirements for locally and easily mounting chip components with high densities.

Please insert the heading -- SUMMARY OF THE INVENTION --, in line 6 on page 5 of the specification.

Please cancel the heading “Means for Solving the Invention,” in line 13 on page 5 of the specification.

Please cancel the heading “Effects of the present invention,” in line 4 on page 13 of

the specification.

Please cancel the heading “Explanation of the Reference Numerals,” in line 17 on page 18 of the specification.

Please delete paragraph [0021].

Please replace the heading “Best Mode for Carrying Out the Invention,” with -- DETAILED DESCRIPTION OF THE INVENTION-- in line 15 on page 19 of the specification.